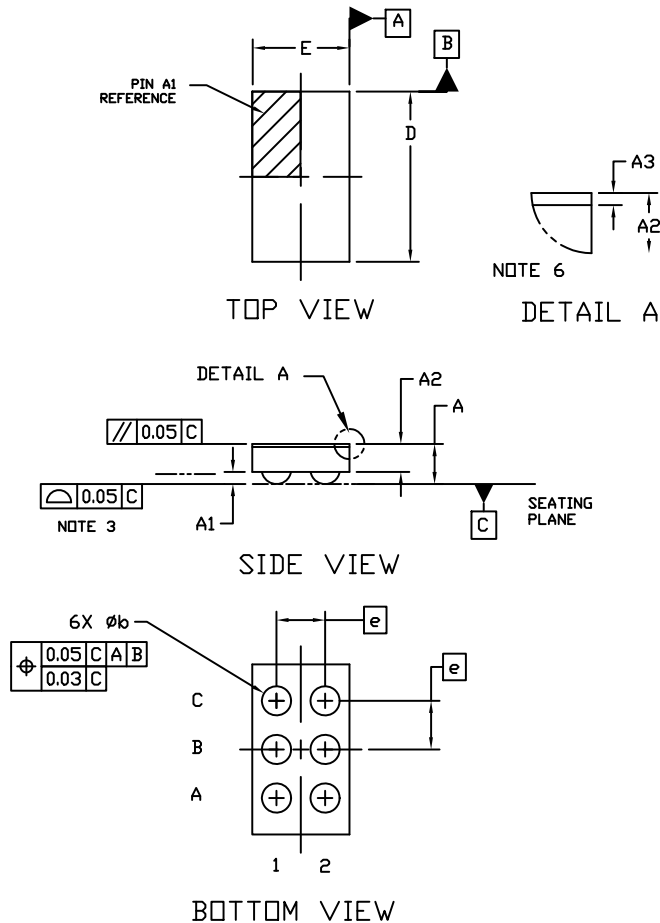


**WLCSP6 1.4x0.8x0.37**  
CASE 567YU  
ISSUE O

DATE 14 NOV 2019


**GENERIC MARKING DIAGRAM\***

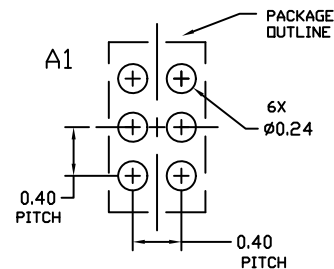
XX = Specific Device Code  
M = Month Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

## NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
4. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
6. BACKSIDE COATING IS OPTIONAL.

| DIM | MILLIMETERS |       |       |
|-----|-------------|-------|-------|
|     | MIN.        | NOM.  | MAX.  |
| A   | ---         | 0.330 | 0.370 |
| A1  | 0.080       | 0.100 | 0.120 |
| A2  | 0.230 REF   |       |       |
| A3  | 0.020       | 0.025 | 0.030 |
| b   | 0.220       | 0.240 | 0.260 |
| D   | 1.370       | 1.400 | 1.430 |
| E   | 0.770       | 0.800 | 0.830 |
| e   | 0.400 BSC   |       |       |


**RECOMMENDED MOUNTING FOOTPRINT**

\* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

|                         |                            |  |
|-------------------------|----------------------------|--|
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| <b>DESCRIPTION:</b>     | <b>WLCSP6 1.4x0.8x0.37</b> | <b>PAGE 1 OF 1</b>   |

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